

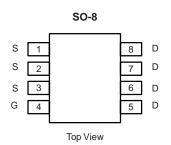
P-Channel 30-V (D-S) MOSFET

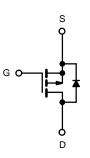
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)		
	0.033 at V _{GS} = - 10 V	- 5.8		
- 30	0.043 at V _{GS} = - 6 V	- 5.0		
	0.056 at V _{GS} = - 4.5 V	- 4.4		

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- Compliant to RoHS Directive 2002/95/EC







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25 ^{\circ}C$, unless otherwise noted					
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	- ;	30	V
Gate-Source Voltage		V_{GS}	± 20		V
Continuo Desir Comment /T 450 9C\2	T _A = 25 °C		- 5.8 - 4.1		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C	ID	- 4.6	- 3.2	^
Pulsed Drain Current		I _{DM}	- 30		Α
Continuous Source Current (Diode Conduction) ^a		I _S	- 2.3	- 1.1	
M	T _A = 25 °C	P _D	2.5	1.3	W
Maximum Power Dissipation ^a	T _A = 70 °C] ^r D	1.6	0.8]
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 t	o 150	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maniana Landina ta Ankin d	t ≤ 10 s	R _{thJA}	40	50	
Maximum Junction-to-Ambient ^a	Steady State	I thJA	70	95	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	24	30	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.



Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 0.7		- 2.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	1	V _{DS} = - 30 V, V _{GS} = 0 V			- 1		
	DSS	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 70 °C			- 5	μA	
	1	$V_{DS} \le -10 \text{ V}, V_{GS} = -10 \text{ V}$ - 20					
On-State Drain Current ^b	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 5			A	
		V _{GS} = - 10 V, I _D = - 5.8 A		0.033			
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = -6 V, I _D = -5 A		0.043		Ω	
		V _{GS} = - 4.5 V, I _D = - 4.4 A		0.056			
Forward Transconductance ^b	g _{fs}	V _{DS} = - 15 V, I _D = - 5.8 A		13		S	
Diode Forward Voltage ^b	V_{SD}	I _S = - 2.3 A, V _{GS} = 0 V		- 0.8	- 1.1	V	
Dynamic ^a							
Total Gate Charge	Q_g			16	24		
Gate-Source Charge	Q_{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -3.5 \text{ A}$		2.3		nC	
Gate-Drain Charge	Q_{gd}			4.5			
Gate Resistance	R_g			8.8		Ω	
Turn-On Delay Time	t _{d(on)}			14	25		
Rise Time	t _r	V_{DD} = - 15 V, R_L = 15 Ω		14	25		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ - 1 A, $V_{GEN}=$ - 10 V, $R_g=$ 6 Ω		42	70	ns	
Fall Time	t _f			30	50		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = - 1.2 A, dI/dt = 100 A/μs		30	60		

Notes:

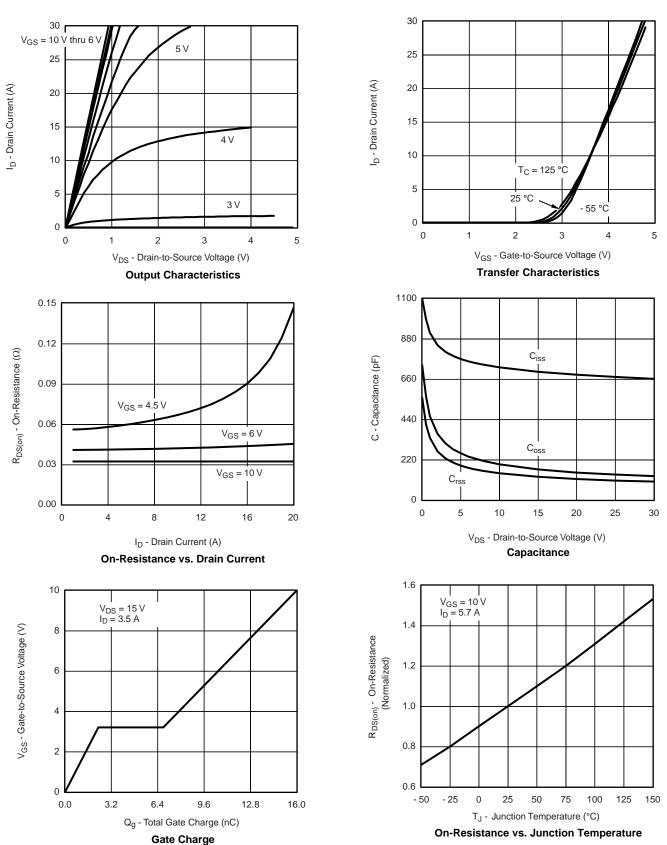
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

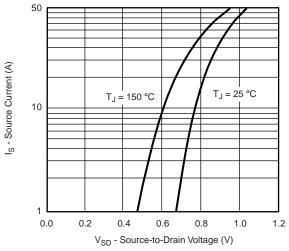


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

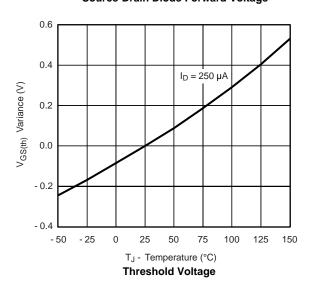


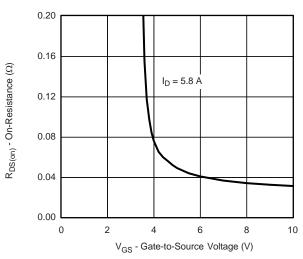


TYPICAL CHARACTERISTICS 25 C, unless otherwise noted

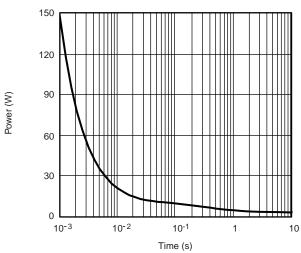




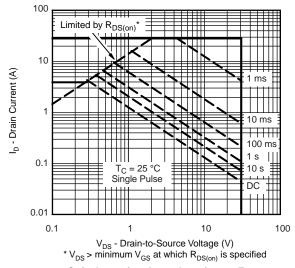




On-Resistance vs. Gate-to-Source Voltage



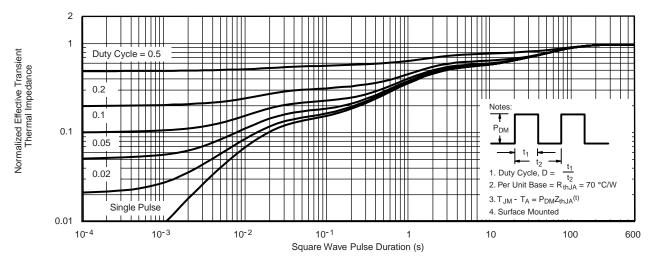
Single Pulse Power, Junction-to-Ambient



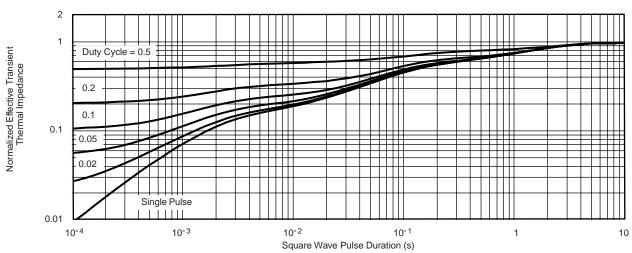
Safe Operating Area, Junction-to-Foot



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

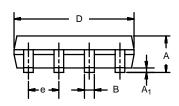


Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







	MILLIMETERS		INC	HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
FCN: C-06527-Rev I 11-Sen-06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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